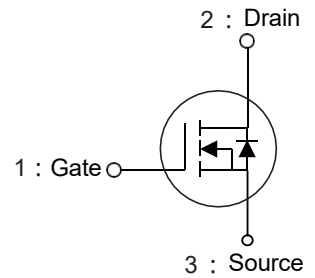


Symbol



■ PRODUCT CHARACTERISTICS

| | |
|-----------------------------------|--------------|
| V_{DSS} | 650V |
| $R_{DS(ON)}$ Typ(@ $V_{GS}=10V$) | 1.1 Ω |
| Qg@typ | 24.5nC |
| I_D | 8A |

■ APPLICATIONS

- * High efficiency switch mode power supplies
- * Electronic lamp ballasts based on half bridge
- * LED power supplies

■ FEATURE

- * High Switching Speed
- * Improved dv/dt capability

■ ORDER INFORMATION



| Order Codes | | Package | Packing |
|--------------|-----------|---------|------------------|
| Halogen-Free | Halogen | | |
| N/A | MOT8N65MD | TO-252 | 2500 pieces/Reel |

■ ABSOLUTE MAXIMUM RATINGS($T_A=25^{\circ}C$, unless otherwise specified)

| Parameter | Symbol | Ratings | Unit |
|--|-----------|-----------|-------------|
| Drain-Source Voltage | V_{DSS} | 650 | V |
| Gate-Source Voltage | V_{GSS} | ± 30 | V |
| Drain Current Continuous(@ $V_{GS}=10V, T_A=25^{\circ}C$) | I_D | 8 | A |
| Drain Current Pulsed | I_{DM} | 32 | A |
| Avalanche Energy * | E_{AS} | 845 | mJ |
| Peak Diode Recovery dv/dt | dv/dt | 5.0 | V/ns |
| Power Dissipation | P_D | 120 | W |
| Junction Temperature | T_J | +150 | $^{\circ}C$ |
| Storage Temperature | T_{STG} | -55~ +150 | $^{\circ}C$ |

■ THERMAL CHARACTERISTICS

| Parameter | Symbol | Typ | Unit |
|---------------------|------------|------|---------------|
| Junction to Ambient | R_{thJA} | 100 | $^{\circ}C/W$ |
| Junction to Case | R_{thJC} | 1.04 | $^{\circ}C/W$ |

Note: * EAS condition: $T_J=25^{\circ}C, V_{DD}=50V, V_G=10V, L=10mH, R_g=25\Omega$

■ ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|---------------------------------------|--------------|---|-----|------|------|----------|
| Off characteristics | | | | | | |
| Drain to Source Breakdown Voltage | V_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 650 | - | - | V |
| Drain to Source Leakage Current | I_{DSS} | $V_{DS}=650V, V_{GS}=0V$ | - | - | 1 | μA |
| Gate to Source Forward Leakage | $I_{GSS(F)}$ | $V_{DS}=0V, V_{GS}=+30V$ | - | - | 100 | nA |
| Gate to Source Reverse Leakage | $I_{GSS(R)}$ | $V_{DS}=0V, V_{GS}=-30V$ | - | - | -100 | nA |
| On characteristics | | | | | | |
| Drain to Source On-Resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=4A$ | - | 1.1 | 1.5 | Ω |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2 | - | 4 | V |
| Dynamic characteristics | | | | | | |
| Gate Resistance | R_g | $V_{GS}=0V, V_{DS}=0V, f=1.0\text{MHz}$ | - | 2.2 | - | Ω |
| Forward Transconductance | g_{fs} | $V_{DS}=10V, I_D=3A$ | - | 6 | - | S |
| Input Capacitance | C_{iss} | $V_{DS}=25V, V_{GS}=0V$ $f=1.0\text{MHz}$ | - | 1200 | - | pF |
| Output Capacitance | C_{oss} | | - | 80 | - | pF |
| Reverse Transfer Capacitance | C_{rss} | | - | 1.9 | - | pF |
| Resistive Switching Characteristics | | | | | | |
| Turn-on Delay Time | $t_{d(ON)}$ | $I_D=8A, V_{DS}=325V$ $R_G=25\Omega, V_{GS}=10V$ | - | 11 | - | ns |
| Rise Time | t_r | | - | 20.5 | - | ns |
| Turn-off Delay Time | $t_{d(OFF)}$ | | - | 80 | - | ns |
| Fall Time | t_f | | - | 32.3 | - | ns |
| Total Gate Charge | Q_g | $I_D=8A, V_{DS}=325V$ $V_{GS}=10V$ | - | 24.5 | - | nC |
| Gate to Source Charge | Q_{gs} | | - | 5.8 | - | nC |
| Gate to Drain("Miller") Charge | Q_{gd} | | - | 6.5 | - | nC |
| Source-Drain Diode Characteristics | | | | | | |
| Continuous Source Current(Body Diode) | I_S | | - | - | 8 | A |
| Maximum Pulsed Current(Body Diode) | I_{SM} | | - | - | 32 | A |
| Diode Forward Voltage | V_{SD} | $I_{SD}=1A, V_{GS}=0V$ | - | 0.72 | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $I_{SD}=8A, T_J=25^{\circ}\text{C}$ | - | 290 | - | ns |
| Reverse Recovery Charge | Q_{rr} | $di/dt=100A/\mu s$ | - | 5920 | - | nC |

■ TYPICAL CHARACTERISTICS

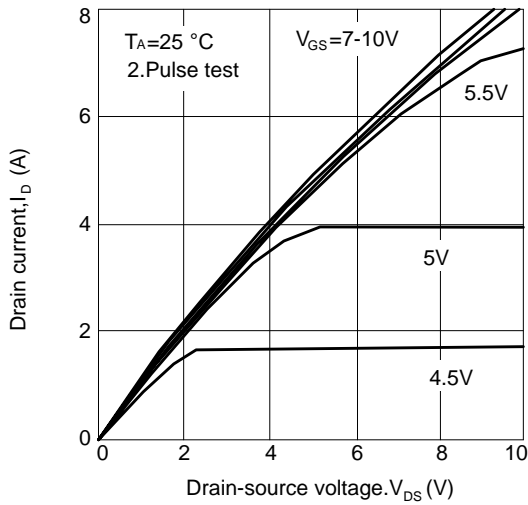


Figure 1: Drain current vs. drain-source voltage

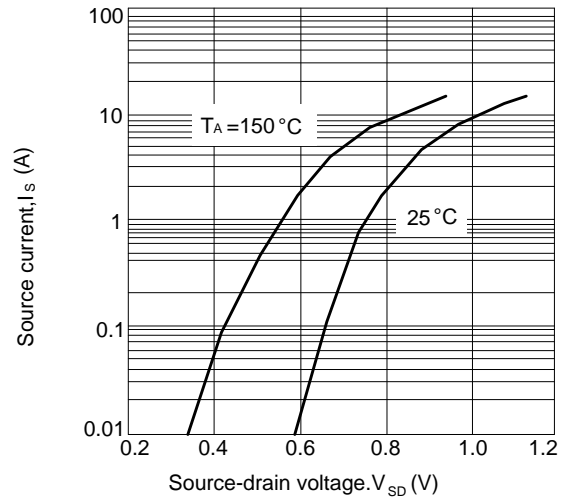


Figure 2: Source current vs. source-drain voltage

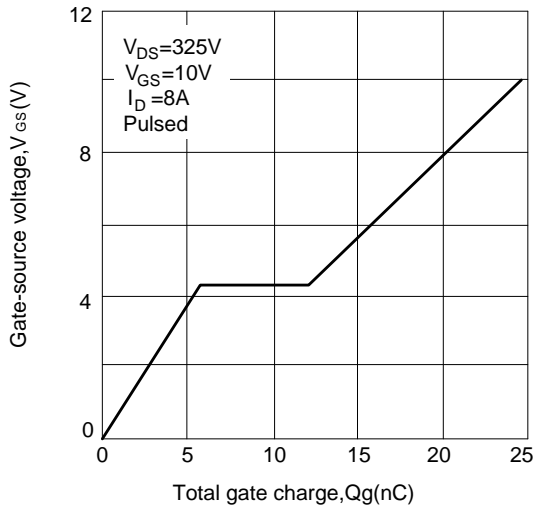


Figure 3: Gate charge characteristics

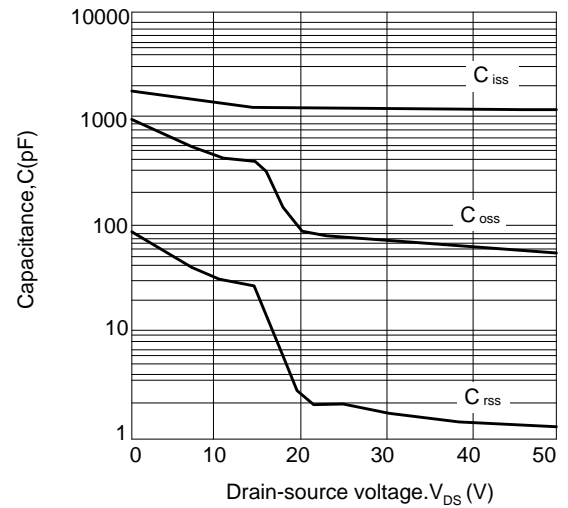


Figure 4: Capacitance characteristics

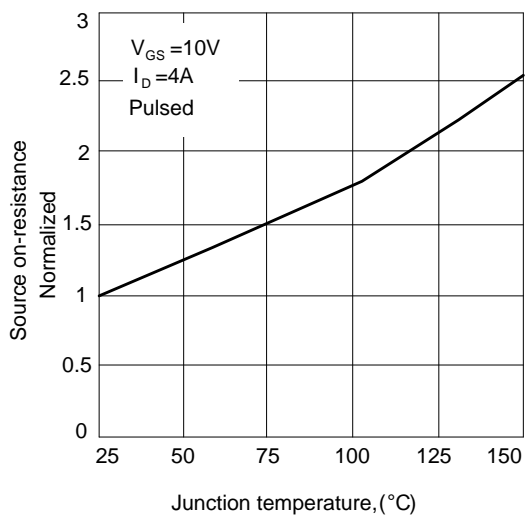


Figure 5: Drain-source on-resistance vs. junction temperature

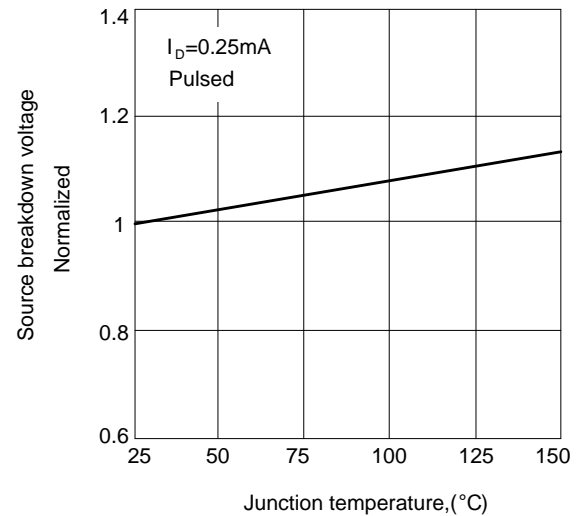


Figure 6: Breakdown voltage vs. junction temperature

■ TYPICAL CHARACTERISTICS(Cont.)

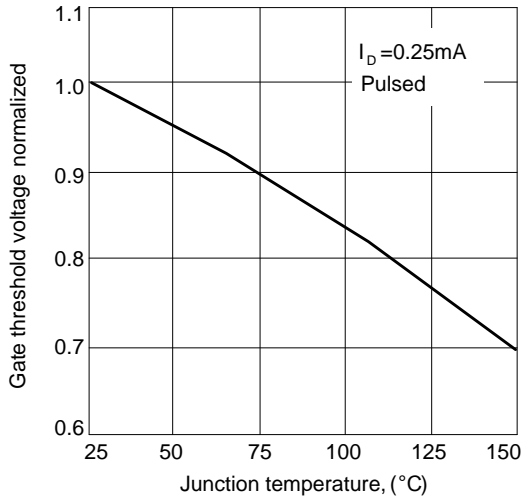


Figure 7: Gate threshold voltage vs. junction temperature

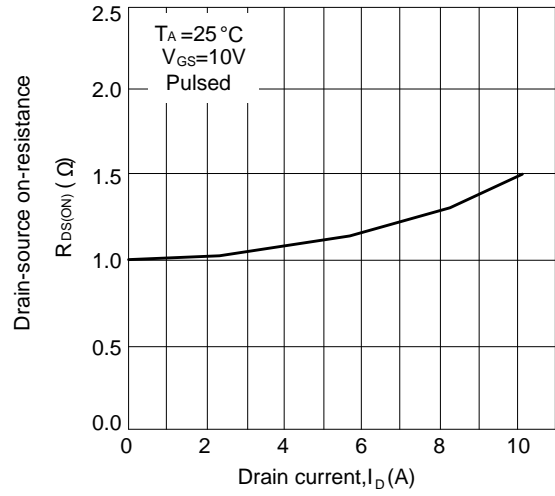


Figure 8: Drain-source on-resistance vs. drain current

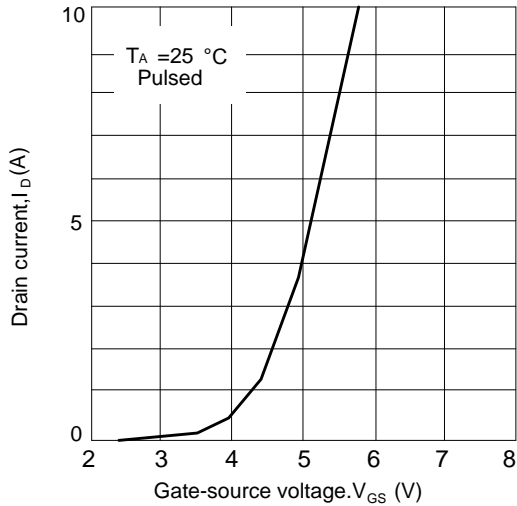


Figure 9: Drain current vs. case-source voltage

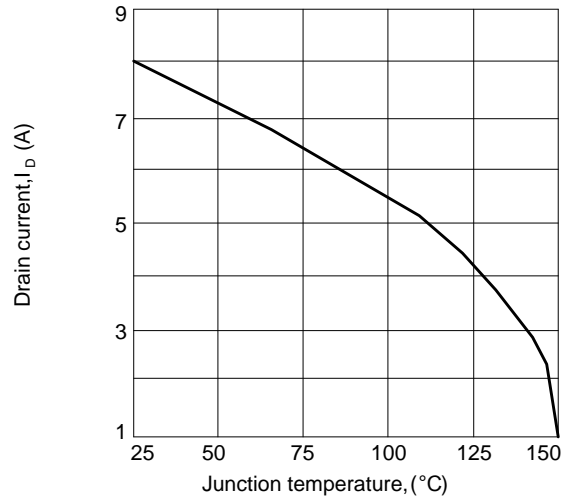


Figure 10: Drain current vs. junction temperature

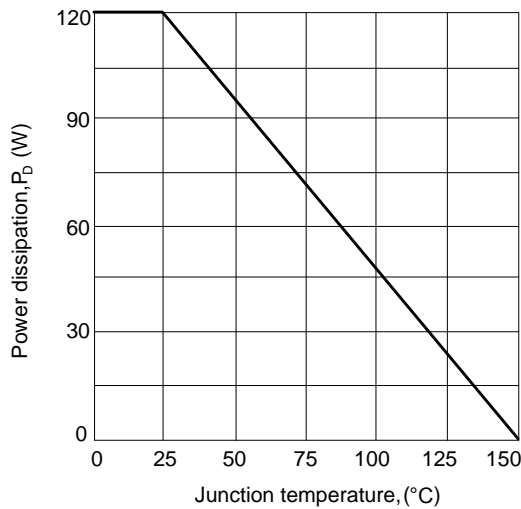


Figure 11: Power dissipation vs. junction temperature

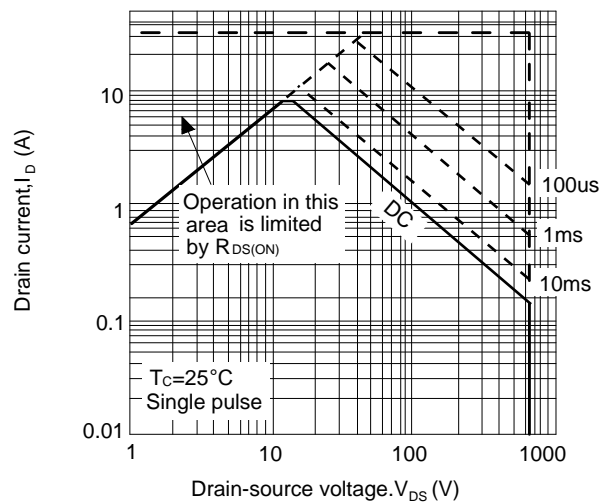


Figure 12: Safe operating area

■ TO-252 PACKAGE OUTLINE DIMENSIONS

